



Material Content Data Sheet



Sales Product Name		ESD203-B1-02ELS E6327		Issued		20. July 2018		
MA#		MA001118068						
Package		PG-TSSLP-2-4		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.33		3341	
	noble metal	gold	7440-57-5	0.003	1.30		12968	
	inorganic material	silicon	7440-21-3	0.020	9.61	11.24	96088	112397
leadframe	non noble metal	nickel	7440-02-0	0.108	51.82	51.82	518186	518186
wire	noble metal	gold	7440-57-5	0.003	1.32	1.32	13241	13241
encapsulation	organic material	carbon black	1333-86-4	0.000	0.17		1692	
	plastics	epoxy resin	-	0.010	4.91		49053	
	inorganic material	silicondioxide	60676-86-0	0.060	28.75	33.83	287548	338293
leadfinish	noble metal	gold	7440-57-5	0.004	1.77	1.77	17681	17681
plating	noble metal	palladium	7440-05-3	0.000	0.01		77	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	125	202
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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